

## 1. General description

Dual ultrafast power diode in a SOT78 (TO-220AB) plastic package.

## 2. Features and benefits

- Fast switching
- Low thermal resistance
- High thermal cycling performance
- Low forward voltage drop
- Reverse surge capability
- Soft recovery characteristic

## 3. Applications

- Output rectifiers in high-frequency switched-mode power supplies

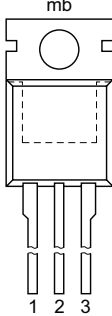
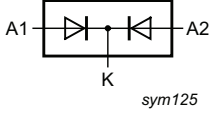
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
<b>Absolute maximum rating</b>						
$V_{RRM}$	repetitive peak reverse voltage		200			V
$I_{O(AV)}$	average output current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 104\text{ °C}$ ; both diodes conducting; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a>	16			A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\ \mu\text{s}$ ; $T_{mb} \leq 104\text{ °C}$ ; square-wave pulse; per diode	16			A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; sine-wave pulse; per diode $T_{j(\text{init})} = 25\text{ °C}$	80			A
		$t_p = 8.3\text{ ms}$ ; sine-wave pulse; per diode $T_{j(\text{init})} = 25\text{ °C}$	88			A
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 8\text{ A}$ ; $T_j = 150\text{ °C}$ ; <a href="#">Fig. 4</a>	-	0.84	0.95	V
<b>Dynamic characteristics</b>						
$t_{rr}$	reverse recovery time	$I_R = 1\text{ A}$ ; $I_F = 0.5\text{ A}$ ; $I_{R(\text{meas})} = 0.25\text{ A}$ ; $T_j = 25\text{ °C}$ ; step recovery; <a href="#">Fig. 6</a>	-	12	22	ns

## 5. Pinning information

**Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode 1		
2	K	cathode		
3	A2	anode 2		
mb	K	mounting base; cathode		

## 6. Ordering information

**Table 3. Ordering information**

Type number	Package		
	Name	Description	Version
BYQ30E-200	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78

## 7. Marking

**Table 4. Marking codes**

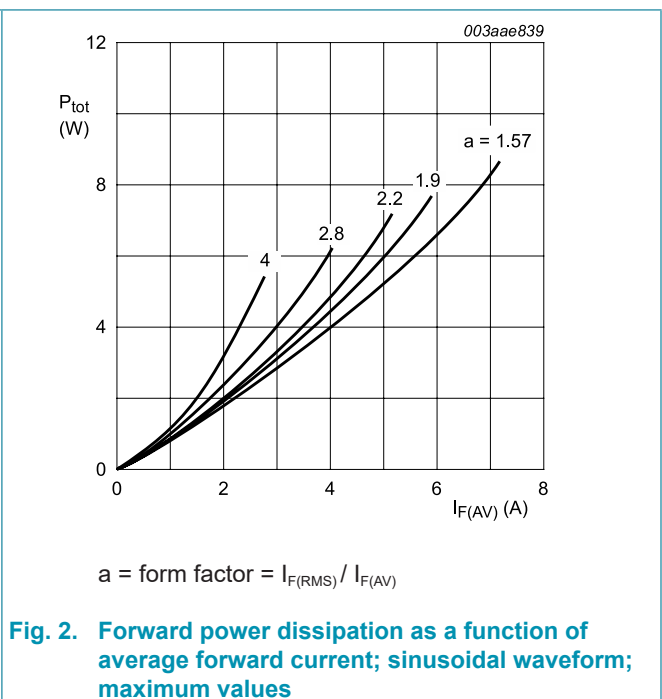
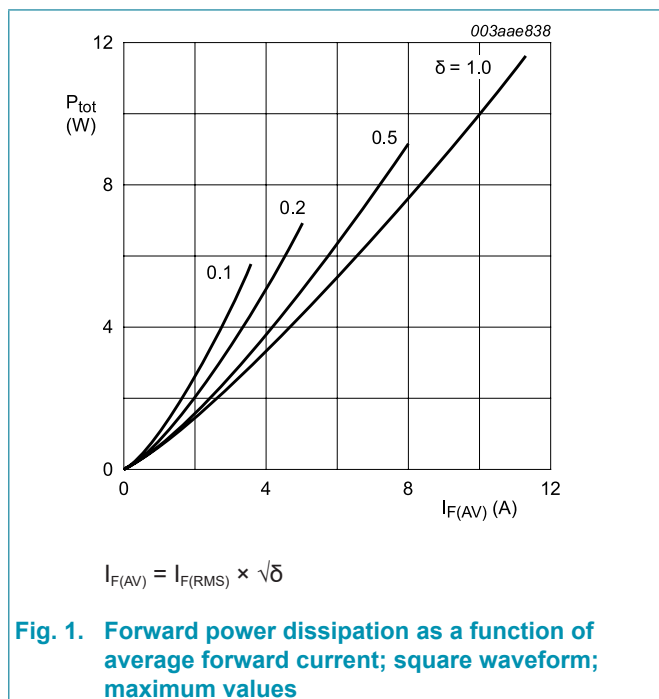
Type number	Marking codes
BYQ30E-200	BYQ30E-200

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

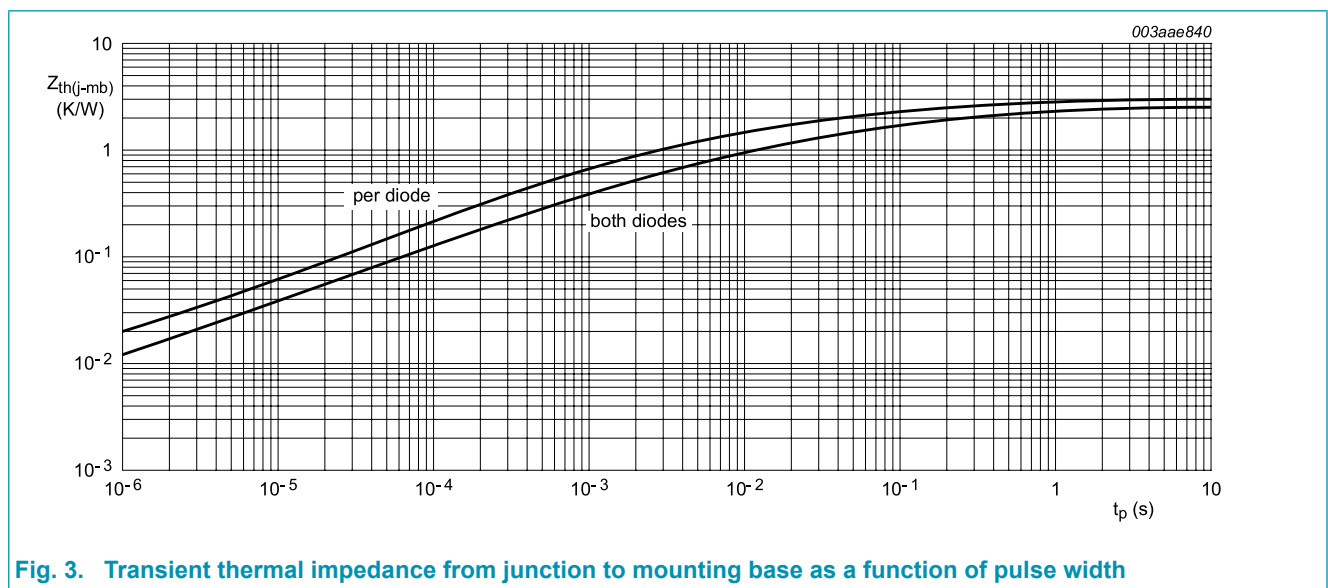
Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		200	V
$V_{RWM}$	crest working reverse voltage		200	V
$V_R$	reverse voltage	DC	200	V
$I_{O(AV)}$	average output current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 104\text{ °C}$ ; both diodes conducting; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a>	16	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\ \mu\text{s}$ ; $T_{mb} \leq 104\text{ °C}$ ; square-wave pulse; per diode	16	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; sine-wave pulse; per diode $T_{j(\text{init})} = 25\text{ °C}$	80	A
		$t_p = 8.3\text{ ms}$ ; sine-wave pulse; per diode $T_{j(\text{init})} = 25\text{ °C}$	88	A
$I_{RRM}$	repetitive peak reverse current	$\delta = 0.001$ ; $t_p = 2\ \mu\text{s}$	0.2	A
$I_{RSM}$	non-repetitive peak reverse current	$t_p = 100\ \mu\text{s}$	0.2	A
$T_{stg}$	storage temperature		-40 to 150	°C
$T_j$	junction temperature		150	°C
<b>Electrostatic discharge</b>				
$V_{ESD}$	electrostatic discharge voltage	HBM; all pins; C = 250 pF; R = 1.5 kΩ	8	kV



## 9. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	with heatsink compound; both diodes conducting; <a href="#">Fig. 3</a>	-	-	2.5	K/W
		with heatsink compound; per diode; <a href="#">Fig. 3</a>	-	-	3	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient		-	60	-	K/W

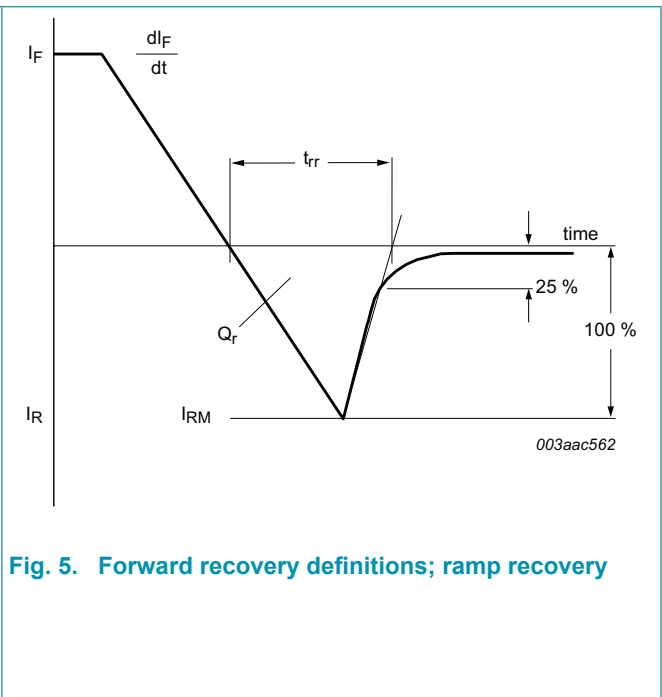
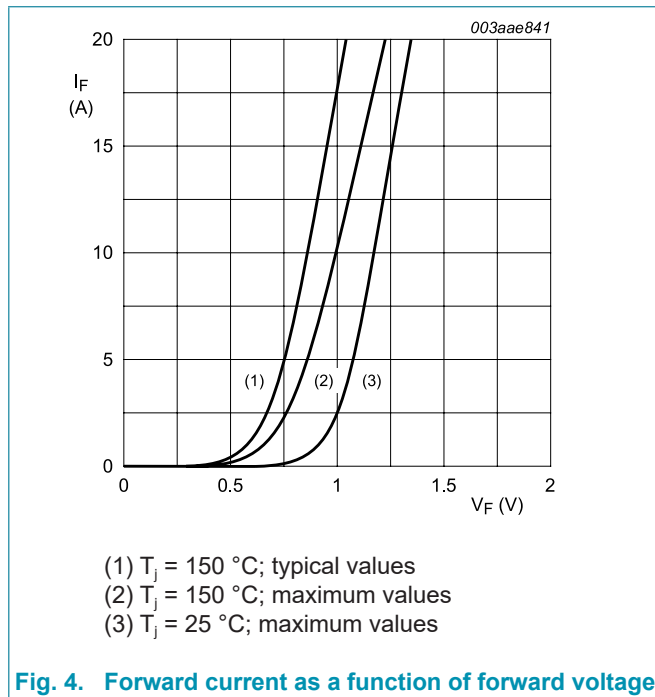


**Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse width**

### 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 16 \text{ A}; T_j = 150 \text{ }^\circ\text{C}; \text{ Fig. 4}$	-	1	1.15	V
		$I_F = 16 \text{ A}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 4}$	-	1.12	1.25	V
		$I_F = 8 \text{ A}; T_j = 150 \text{ }^\circ\text{C}; \text{ Fig. 4}$	-	0.84	0.95	V
$I_R$	reverse current	$V_R = 200 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	4	30	$\mu\text{A}$
		$V_R = 200 \text{ V}; T_j = 100 \text{ }^\circ\text{C}$	-	0.3	0.6	mA
<b>Dynamic characteristics</b>						
$Q_r$	recovered charge	$I_F = 2 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 20 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 5}$	-	4	11	nC
$t_{rr}$	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A}/\mu\text{s}; \text{ ramp recovery}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 5}$	-	20	25	ns
		$I_F = 0.5 \text{ A}; I_R = 1 \text{ A}; \text{ step recovery}; I_{R(\text{meas})} = 0.25 \text{ A}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 6}$	-	12	22	ns
$V_{FR}$	forward recovery voltage	$I_F = 1 \text{ A}; dI_F/dt = 10 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{ Fig. 7}$	-	1	-	V



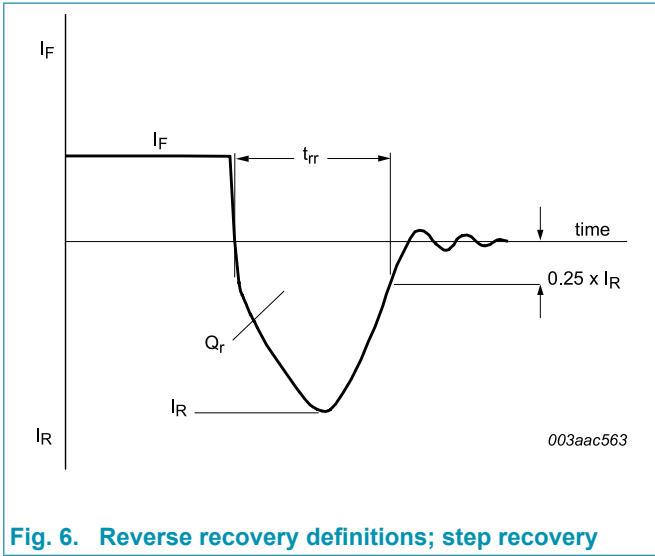


Fig. 6. Reverse recovery definitions; step recovery

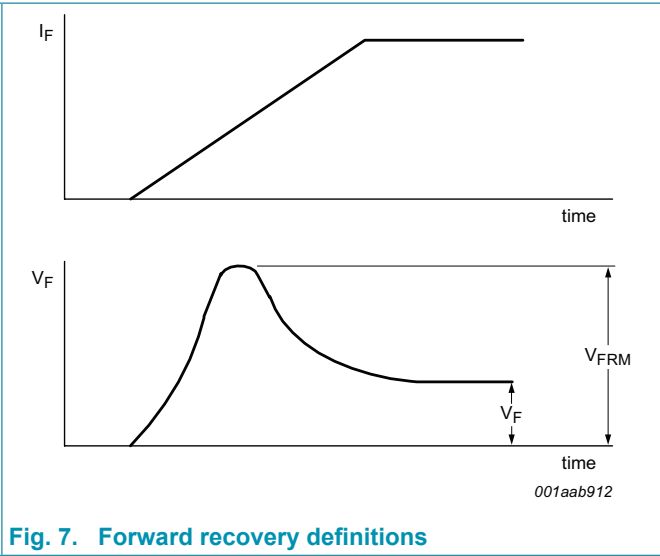
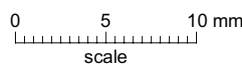
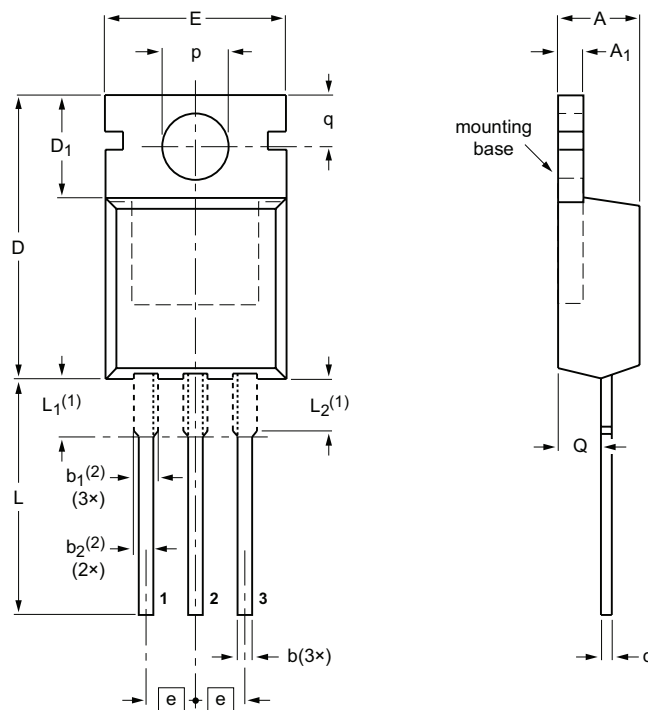


Fig. 7. Forward recovery definitions

### 11. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



**DIMENSIONS** (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b	b <sub>1</sub> (2)	b <sub>2</sub> (2)	c	D	D <sub>1</sub>	E	e	L	L <sub>1</sub> (1)	L <sub>2</sub> (1) max.	p	q	Q
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.6 1.0	1.3 1.0	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

**Notes**

- 1. Lead shoulder designs may vary.
- 2. Dimension includes excess dambar.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT78		3-lead TO-220AB	SC-46		08-04-23 08-06-13

## 12. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BYQ30E-200 v.5	20180605	Product data sheet	-	BYQ30E-200 v.4
Modifications:	Change from NXP version to WeEn version			
BYQ30E-200 v.4	20100901	Product data sheet	-	BYQ30E_SERIES_3
Modifications:	<ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li>Type number BYQ30E-200 separated from datasheet BYQ30E_SERIES.</li> </ul>			
BYQ30E_SERIES_3	19981001	Product specification	-	BYQ30E_SERIES_2

## 13. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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